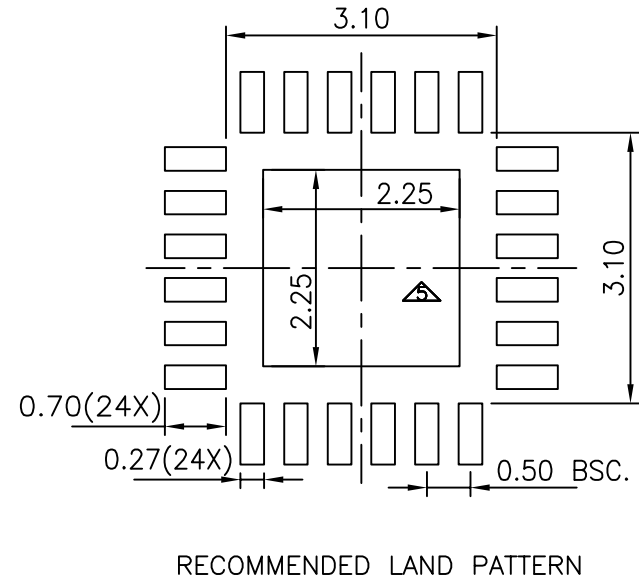
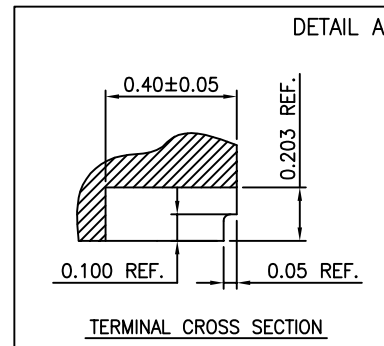


| SYMBOLS | MIN.      | NOM. | MAX. |
|---------|-----------|------|------|
| A       | 0.80      | 0.85 | 0.90 |
| A1      | 0.00      | 0.02 | 0.05 |
| A3      | 0.20 REF. |      |      |
| b       | 0.18      | 0.25 | 0.30 |
| D       | 3.90      | 4.00 | 4.10 |
| E       | 3.90      | 4.00 | 4.10 |
| e       | 0.50 BSC  |      |      |
| D2      | 2.20      | 2.25 | 2.30 |
| E2      | 2.20      | 2.25 | 2.30 |
| L       | 0.35      | 0.40 | 0.45 |



DATE: 07/09/21

**DIODES** **PERICOM** A PRODUCT LINE OF DIODES INCORPORATED  
INCORPORATED ENABLING SERIAL CONNECTIVITY

DESCRIPTION: V-QFN4040-24 (SWP)

PACKAGE CODE: ZDW (ZDW24)

DOCUMENT CONTROL #: PD-2269

REVISION: --

NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA